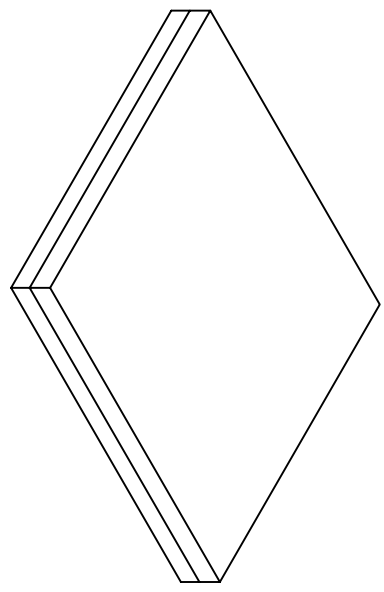


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REV	DESCRIPTION	DATE	DESIGNED BY	CHECKED BY
00	INITIAL RELEASE PER DCN C06437	04/06/99	E.B.	L.J.M.



7. REFERENCE SPECIFICATIONS:
 A. AAW SPEC #001-0591-2234: PACKING OPERATION PROCEDURE.
 B. AAW SPEC #001-0519-2092: MARKING.
 6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
 4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 169.
 3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 16 X 16.
 2. THE BASIC SOLDER BALL GRID PITCH IS 0.80.
 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		ANGULAR ±1°	
XX ±0.10			
XXX ±0.05			
XXXX ±0.03			
MATERIAL	N/A		
FINISH	N/A		

FUNCTION	APPROVALS	DATE
		09/17/99
		09/17/99
		09/17/99
		04/06/99

AAW Industrial Co., Ltd. Shanghai-Hk, Seoul, Korea	AIRCOR Electronics, Inc. Chandler, Arizona, USA
PACKAGE OUTLINE - CABGA 192, 14.00mm X 14.00mm, 2 LAYER, 0.80mm PITCH, LAMINATE SUBSTRATE, AAP	
REV	DATE
B	N/A
DATE PREPARED/REV/DATE CODE	DATE RELEASED
N/A	74750